



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: .VariantName

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TMDXICE110	REV: 1.1	SVN REV: Not In VersionControl
	TID #: NA		
PLOT NAME = Multilayer Composite Print	GENERATED : 12/26/2016	8:48:53 PM	TEXAS INSTRUMENTS

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